



Honeywell DE Master Communication Interface Module

MVI56-DEM

Supported Honeywell instruments include:

- ST 3000 smart pressure transmitter
- STT 3000 smart temperature transmitter
- SMV 3000 smart multivariable transmitter
- MagneW 3000 smart magnetic flowmeter
- SCM 3000 smart coriolis mass flowmeter
- SGC 3000 smart gas chromatograph

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Honeywell DE Master Communication Module

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The MVI56 DE Master Communication Module allows Rockwell Automation ControlLogix I/O compatible processors to interface easily with Honeywell DE instruments. Compatible devices include a large array of field devices including pressure, temperature, metering and many other instruments.

Features and Benefits

The module supports 16 DE channels, allowing both single and/or multivariable Honeywell transmitters operating in the DE mode to be directly integrated in the Rockwell Automation environment.

Data exchange between the DEM module and the processor data table is performed using standard ladder logic. Included in system is the pre-programmed ControlLogix, rack and power supply, the DEM module and the Honeywell field terminal assembly and cable.

General Specifications

- Single Slot – 1756 backplane compatible
- Local or remote rack
- The module is recognized as an Input/Output module and has access to processor memory for data transfer between processor and module
- Ladder Logic is used for data transfer between module and processor.
- Configuration data obtained through user-defined ladder. Sample ladder file included

Hardware Specifications

Specification	Description
Backplane Current Load	800 mA @ 5 V
Operating Temperature	0 to 60°C (32 to 140°F)
Storage Temperature	-40 to 85°C (-40 to 185°F)
Shock:	30g Operational 50g non-operational
	Vibration: 5 g from 10 to 150 Hz
Relative Humidity	5 to 95% (non-condensing)
LED Indicators:	Module Status Backplane Transfer Status Application Status Serial Activity

